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Pixus Announces New Conduction Cooled ATRs and Specialty Enclosures

Waterloo, Ontario — May 3, 2016 – Pixus Technologies, a provider of embedded computing and enclosure solutions, now offers conduction cooled chassis in the ATR format or in specialty Small Form Factor (SFF) designs. Enclosures formats are available for both OpenVPX and MicroTCA architectures.

The Pixus conduction-cooled ATRs come in standard 1/2 and 3/4 sizes for 3U or 6U boards. There are also options for the MicroTCA.3 Hardened form factor as well as heat exchanged versions. The enclosures are designed to meet MIL-STD-704, MIL-STD-810G, and MIL-STD-461. Off-the-shelf power interface boards are available to easily incorporate VITA 62 or PICMG 2.9 power supplies. For specialty designs or those looking to minimize Size, Weight, and Power (SWaP), Pixus also offers application-specific conduction cooled solutions.

Pixus provides rugged and 19” rackmount enclosures in multiple backplane architectures including OpenVPX, MicroTCA, AdvancedTCA, and legacy CompactPCI/VME. The company also provides specialty backplanes and handle/panel sets for embedded boards.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.